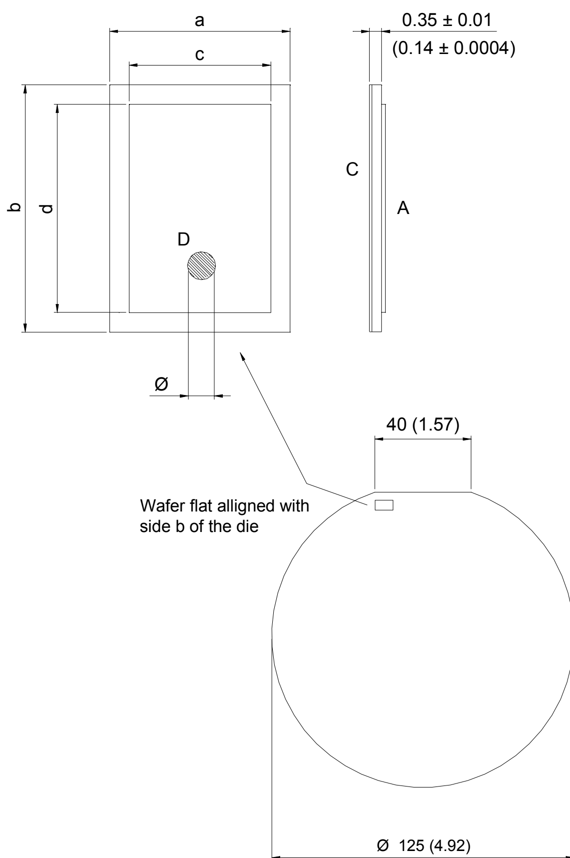
International
IOR Rectifier

Bulletin I0506J rev. B 10/00

SC170.....5. Series

SCHOTTKY DIE 115 x 170 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

2. CONTROLLING DIMENSION: (INCH).

3. DIMENSIONS AND TOLERANCES:
   a = 4.32 + 0, - 0.05
   (0.170 + 0, - 0.002)
   b = 2.92 + 0, - 0.05
   (0.115 + 0, - 0.002)
   c = 4.17 + 0, - 0.003
   (0.164 + 0, - 0.0001)
   d = 2.77 + 0, - 0.003
   (0.109 + 0, - 0.0001)
   Ø = 0.7 ± 0.1
   (0.03 ± 0.004)

4. LETTER DESIGNATION:
   A = Anode (Top Metal)
   C = Cathode (Back Metal)
   D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:
   Recommended Blade
   SEMITEC S1025 QS00 Blade

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only. Contact factory for information.

Electrical Characteristics

Device #	T_J Max. (°C)	V_R (V)	Typ. I_R @ 25°C (µA)	Typ. I_R @ 125°C (mA)	Max. V_F @ I_F (V)	Package Style
SC170**R**015x5x	125	15	5000	600	0.41 @ 19A	TO-220
SC170**S**020x5x	150	20	n.a. contact factory			
SC170**S**030x5x	150	30	350	140	0.48 @ 20A	TO-220
SC170**S**045x5x	150	45	250	100	0.57 @ 20A	TO-220
SC170**S**060x5x	150	60	140	70	0.61 @ 20A	TO-220
SC170**H**045x5x	175	45	40	14	0.60 @ 18A	TO-220
SC170**H**100x5x	175	100	15	8	0.80 @ 20A	TO-220
SC170**H**150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC170xxxx**A**5x	Wire Bondable	–	Al 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC170xxxx**S**5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.
Shelf life for parts stored in above condition is 2 years.
If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC170xxxxx5**B**	Inked Probed Unsawn Wafer (Wafer in Box)	800
SC170xxxxx5**R**	Probed Die in Tape & Reel	n.a.
SC170xxxxx5**P**	Probed Die in Waffle Pack	800
SC170xxxxx5**F**	Inked Probed Sawn Wafer on Film	800

Ordering Information Table

Device Code

SC	170	H	100	S	5	B
1	2	3	4	5	6	7

1 - Schottky Die

2 - Chip Dimension in Mils

3 - Process (see Electrical Characteristics Table)

4 - Voltage code: Code = V_{RRM}

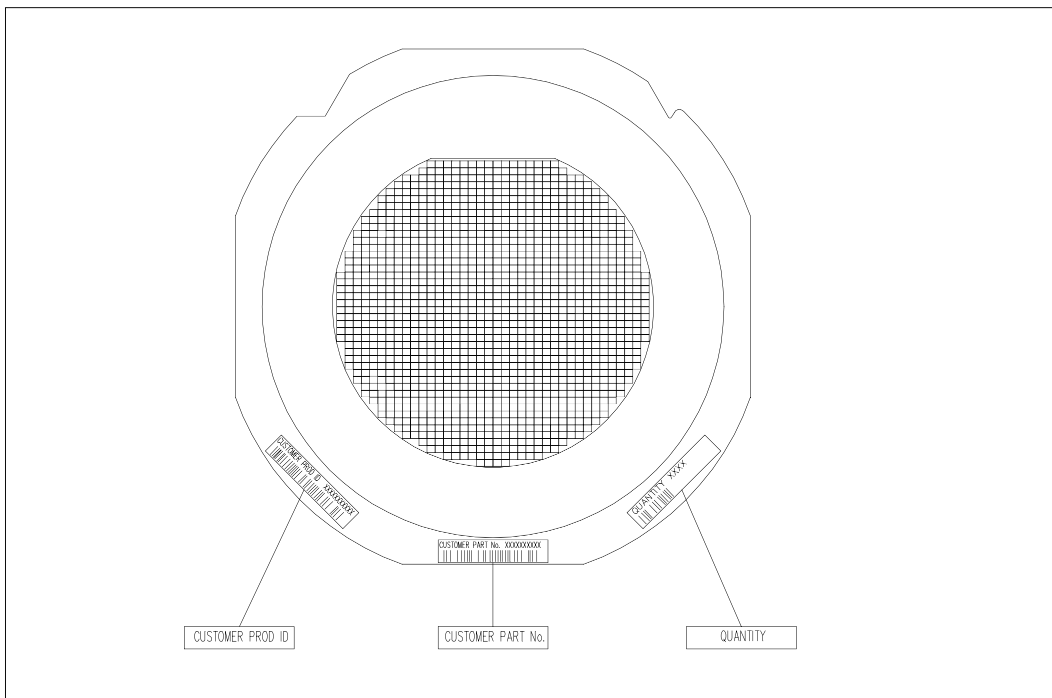
5 - Chip surface metallization (see Mechanical Data Table)

6 - Wafer Diameter in inches

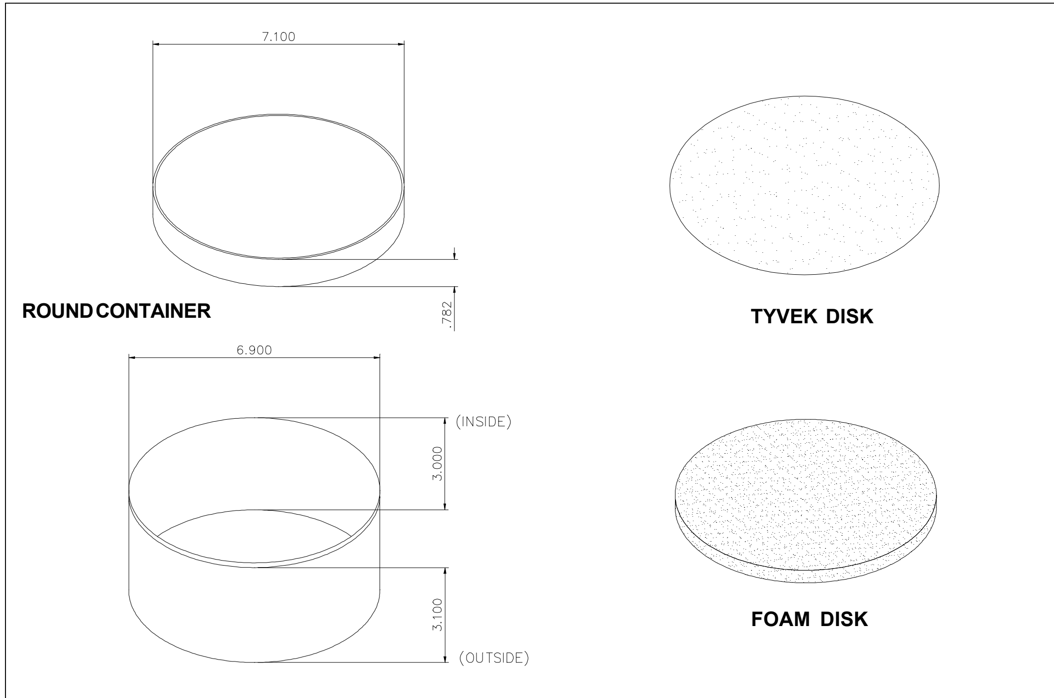
7 - Packaging (see Packaging Table)

H = 830 Process
R = OR'ing Process
S = Standard Process

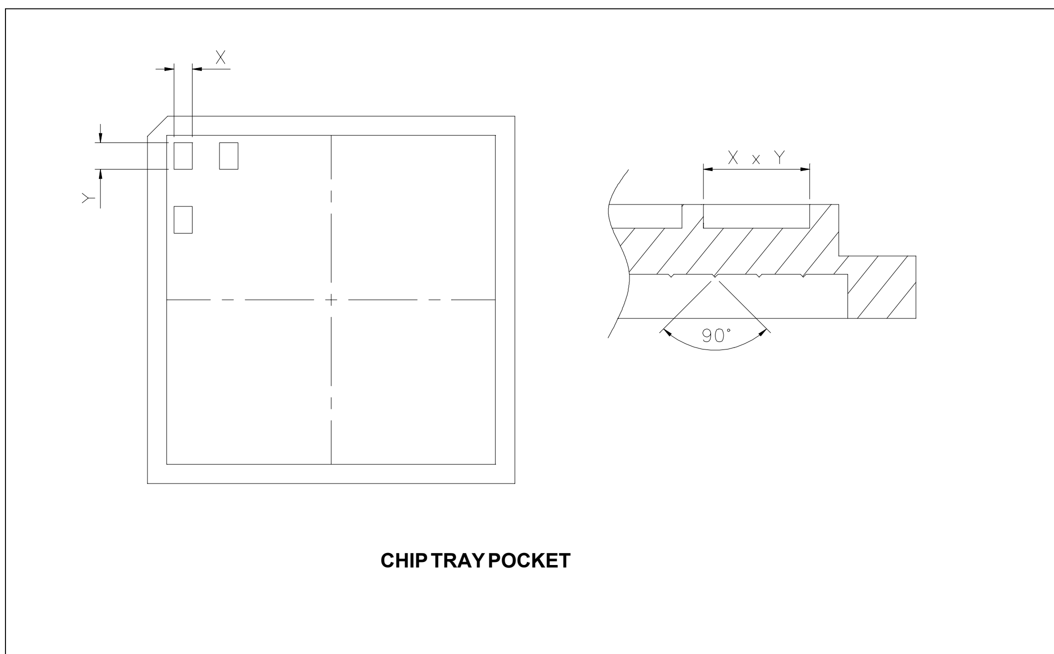
Wafer on Film



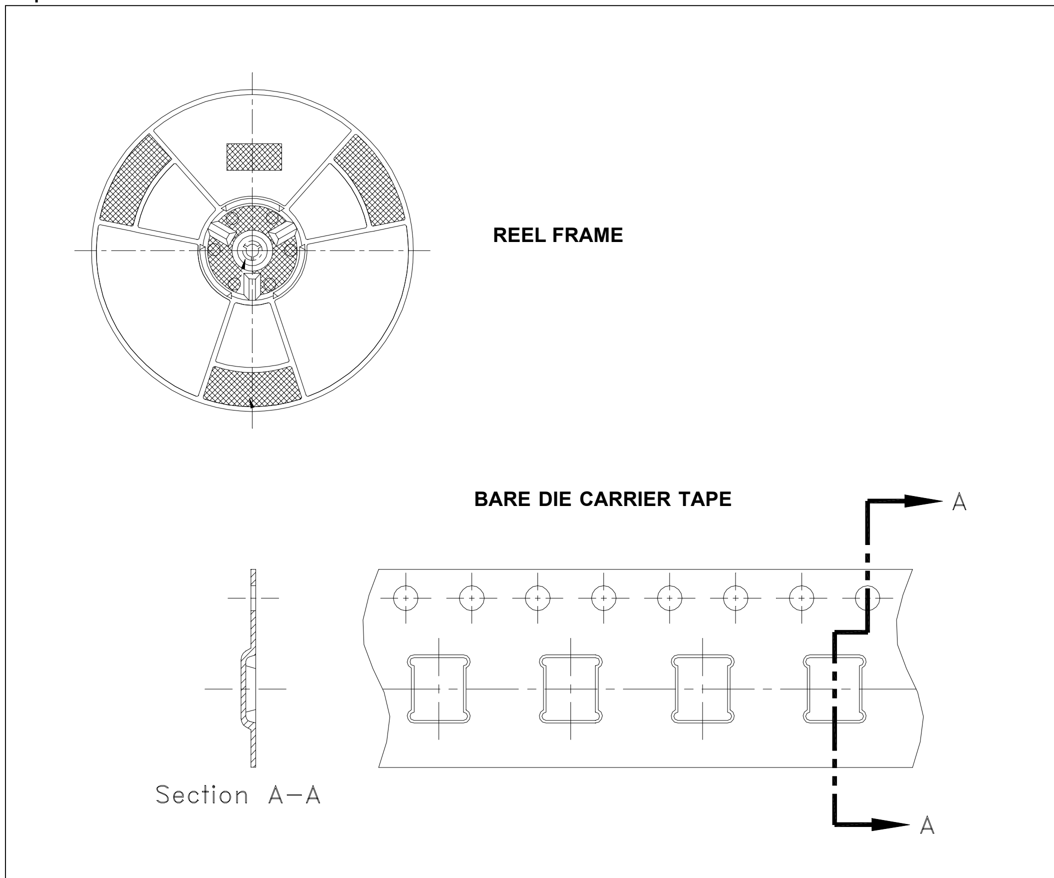
Wafer in Box



Die in Waffle Pack



Tape and Reel



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